

	Room A	Room B1	Room B2	Room K
09:00	<p>(10:00)</p> <p>[14A-1] High Performance Flip-Chip Packaging</p> <ol style="list-style-type: none"> 1. Packaging Technologies for High Performance Computing System (Session Invite) J.Inasaka (NEC)/Japan 2. Spatial/Transient Thermal Resistance for High Performance FC Packages (Session Invite) K.Yazawa (SONY)/Japan 3. Facing Issues for Next Generation High Density Build Up Package Fabrication and the Alternative Solutions (Session Invite) S.Koyama (Shinko Electric Industries)/Japan 4. Power Integrity Optimization for a High-performance Microprocessor in Low-cost Systems S.Suminaga, H.Mori, T.Nishio (IBM Japan) /Japan 	<p>(10:00)</p> <p>[14B1-1] Embedded Substrate I</p> <ol style="list-style-type: none"> 1. WLP-IC Embedded Multi-layer Polyimide Wiring Board S.Okude (Fujikura)/Japan 2. Development of Embedded Passive / Active Devices Technology for Simultaneous Pressing Process H.Kamiya (DENSO)/Japan 3. IMB Technology for Embedded Active and Passive Components in SIP, SiB and Single IC Package Applications R.Tuominen, T.Waris, J.Mettovaara (Imbera Electronics)/Finland 	<p>(10:00)</p> <p>[14B2-1] Optoelectronics I</p> <ol style="list-style-type: none"> 1. Adaptive Quad 10-Gbps Optical I/O Module for Power-Minimized Interconnection R.Kuribayashi, I.Hatakeyama, D.Inami, T.Hino, T.Sugimoto, K.Kurata (NEC)/Japan 2. Low-Loss, Chip-Based Optical Interconnects on Waveguide-Integrated SLC S.Nakagawa¹, H.Numata¹, Y.Taira¹, K.Kobayashi², K.Terada², M.Fukui² (¹IBM, ²Kyocera SLC Technologies)/Japan, 3. Embedded Micromirror Fabricated by Using Liquid Immersion Exposure for Thin Film Optical Interconnects K.Shimizu, T.Muranishi, J.Inoue, K.Nishio, K.Kintaka, Y.Awatsuji, S.Ura (Kyoto Institute of Technology)/Japan 	<p>[14K-1] Energy / Environment</p> <ol style="list-style-type: none"> 1. The IP Landscape for Photovoltaics C.E.Bauer, R.A.Fillion, H.J.Neuhaus (TechLead) /USA 2. Developing Direct Methanol Fuel Cell from Basic Research Results; Process View A.Suominen¹, R.Jokinen², M.Fonsell³, A.Tuominen¹ (¹University of Turku, ²Turku University of Applied Sciences) /Finland 3. Developing Direct Methanol Fuel Cell from Basic Research Results; Technical Aspects R.Jokinen¹, A.Suominen¹, M.Fonsell³, A.Tuominen¹ (¹University of Turku, ²Turku University of Applied Sciences) /Finland 4. Innovative Jisso Structure by Skeleton Circuit Structure H.Hayashi (The University of Tokyo) /Japan <p>(10:40)</p> <p>[14K-2] Lead Free / Environment</p> <ol style="list-style-type: none"> 1. Effect of Mn Addition on Properties of Sn-Ag-Cu-In Quaternary Lead-free Solder Alloy A.-M.Yu¹, J.-K.Kim¹, J.-H.Lee², M.-S.Kim² (¹Korea Institute of Industrial Technology, ²Seoul National University of Technology, ³Inha University) /Korea 2. Inhibition of Cracking in Cu₆Sn₅ Intermetallic Compounds at Sn-Cu Lead-Free Solders and Cu Substrate Interfaces K.Nogita¹, S.Suenaga², S.D.McDonald¹, H.Tsukamoto¹, J.Read¹, T.Nishimura² (¹The University of Queensland, ²Nihon Superior) /Australia, Japan 3. Impact Strength of Sn-Cu-(Ni) Lead-Free Solder Ball Grid Arrays Placed on Cu Substrates H.Tsukamoto¹, T.Nishimura², S.Suenaga², S.D.McDonald¹, J.Read¹, K.Nogita¹ (¹The University of Queensland, ²Nihon Superior) /Australia, Japan 4. Microstructure and Mechanical Properties of Sn-Bi Eutectic Solder S.Sakuyama (Fujitsu Laboratories)/Japan <p>(12:30)</p>
11:15				
11:25	<p>(11:40)</p>	<p>[14B1-2] Embedded Substrate II</p> <ol style="list-style-type: none"> 1. Feasibility Study of Designing RF Band-pass Filters Using Embedded Passives Technique on Organic Substrate K.-C.Chin (Industrial Technology Research Institute)/Taiwan 2. Experimental Study of High Speed Transmission Performance of Substrate with Embedded Active Device M.Tanaka (Dai Nippon Printing)/Japan 3. Fabrication of Thin-Film Capacitors Using Aerosol CVD for High Performance Ceramic Package Applications S.Wang, A.Hattori, Y.Ozeki, W.Zhang, H.Ogawa (Noda Screen)/Japan 	<p>[14B2-2] Optoelectronics II</p> <ol style="list-style-type: none"> 1. Multimode Polymer Optical Waveguide with Graded-Index Rectangular Cores for Optical Printed Circuit Board T.Kosugi (Keio University)/Japan 2. Reflowable Surface Mount Optical Encoder J.Hane, Y.Kuroda, H.Fujita, T.Ito, I.Komazaki, E.Yamamoto (Olympus)/Japan 3. Reliability Improvement of Optical Devices by Using Newly Developed Highly Moisture Durable Optical Adhesives S.Mitachi (Tokyo University of Technology) /Japan 	
12:40				
12:40	<p>Lunch time</p> <p>Poster Session</p>	<p>Lunch time</p> <p>Poster Session</p>	<p>Lunch time</p> <p>Poster Session</p>	<p>Lunch time</p> <p>Poster Session</p>
13:40	<p>Japanese Noh Drama (Room A)</p>			
13:55	<p>Welcome Ceremony & Awarding Ceremony ICEP2008 (Room A)</p>			
14:25	<p>Invited Speeches (Room A)</p>			
14:25	<ol style="list-style-type: none"> 1. Packaging Technology Roadmap - An IBM Perspective Peter Brofman (IBM) 2. Memory Packaging Strategy with Sophisticated Technology Takayuki Watanabe (Akita Elpida Memory) 3. Photovoltaic as An Energy Solution Tetsuroh Muramatsu (Sharp) 			
17:35				
18:00	<p>Welcome Reception (Banquet Hall "Swan")</p>			
20:00				